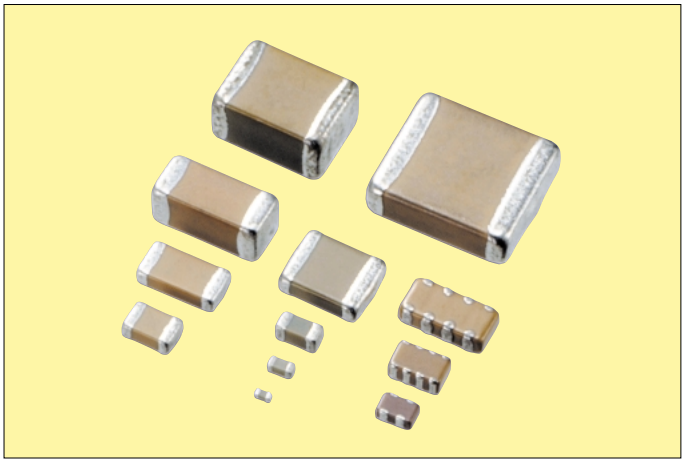
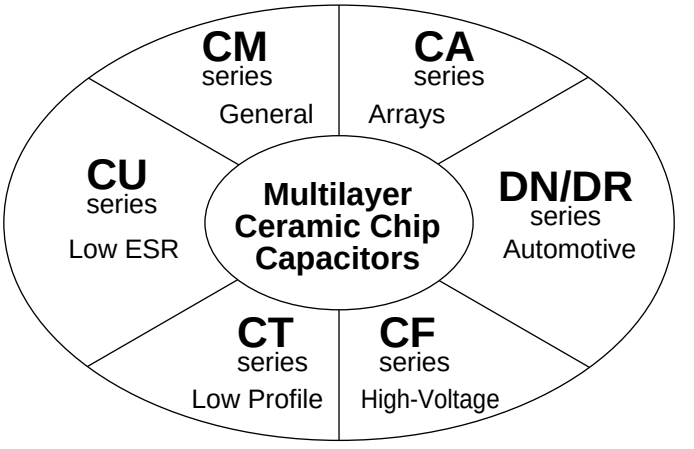
Kyocera's series of Multilayer Ceramic Chip Capacitors are designed to meet a wide variety of needs. We offer a complete range of products for both general and specialized applications, including the general-purpose CM series, the high-voltage CF series , the low profile CT series, and the DN series for automotive uses.

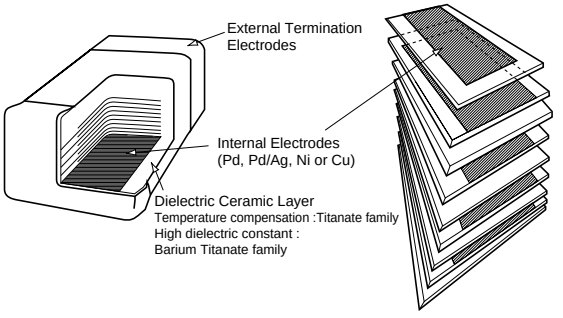


Features

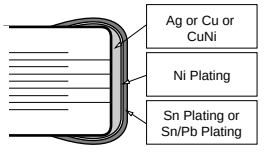
- We have factories worldwide in order to supply our global customer bases quickly and efficiently and to maintain our reputation as the highest-volume producer in the industry.
- All our products are highly reliable due to their monolithic structure of high-purity and superfine uniform ceramics and their integral internal electrodes.
- By combining superior manufacturing technology and materials with high dielectric constants, we produce extremely compact components with exceptional specifications.
- Our stringent quality control in every phase of production from material procurement to shipping ensures consistent manufacturing and super quality.
- Kyocera components are available in a wide choice of dimensions, temperature characteristics, rated voltages, and terminations to meet specific configurational requirements.



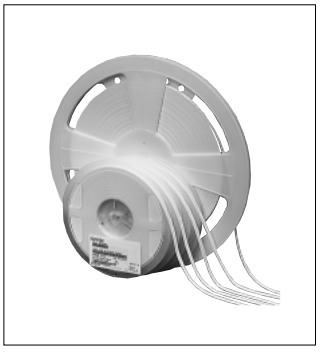
Structure



Nickel Barrier Termination Products



Tape and Reel



Bulk Cassette

Please contact your local AVX sales office or distributor for specifications not covered in this catalog.

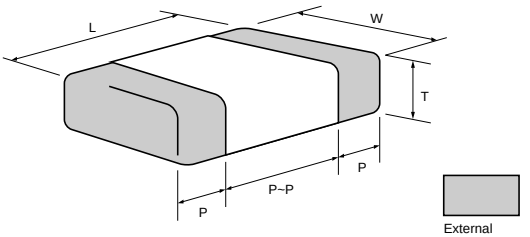
Our products are continually being improved. As a result, the capacitance range of each series is subject to change without notice. Please contact an sales representative to confirm compatibility with your application.

Kyocera Ceramic Chip Capacitors are available for different applications as classified below:

Series	Dieletric Options	Typical Applications	Features	Terminations	Available Size (EIA)
CM	C0G (NP0) X5R X7R X6S X7S Y5V NTC*	General Purpose	Wide Cap Range	Nickel Barrier	0201, 0402, 0603 0805, 1206, 1210 1812, 2211, 2220
CF	C0G (NP0) X7R	High Voltage & Power Circuits	High Voltage 250VDC, 630VDC 1000VDC, 2000VDC 3000VDC, 4000VDC	Nickel Barrier	0805, 1206, 1210 1812, 2208, 1808 2220
CT	C0G (NP0) X5R X7R Y5V	PLCC (Decoupling)	Low Profile	Nickel Barrier	0402, 0603, 0805 1206, 1210
***DN/DR**	C0G (NP0) U (750) X7R, X8R	Automotive	Thermal shock Resistivity High Reliability	Nickel Barrier	0603, 0805, 1206
CU	C0G (NP0)	RF Circuit	Low ESR	Nickel Barrier	0402, 0603
CA	C0G (NP0) X5R	Digital Signal Pass line	Reduction in Placing Costs	Nickel Barrier	0405, 0508, 0612

* NTC: Negative Temperature coefficient types are available on request.
* DN Series: Silver Palladium termination is available on request.
* CA Series: X7R, Y5V are available on request.

Dimensions



External Dimensions

Tape & Reel

Size	EIA CODE	EIAJ CODE	Dimensions (mm)					
			L	W	P min	P max	P to P min	T max
03	0201	0603	0.6±0.03	0.3±0.03	0.10	0.20	0.20	0.33
05	0402	1005	1.0±0.05	0.5±0.05	0.15	0.35	0.30	0.55
105	0603	1608	1.6±0.10	0.8±0.10	0.20	0.60	0.50	0.90
21	0805	2012	2.0±0.10	1.25±0.10	0.20	0.75	0.70	1.35
316	1206	3216	3.2±0.20	1.60±0.15	0.30	0.85	1.40	1.75
32	1210	3225	3.2±0.20	2.50±0.20	0.30	1.00	1.40	2.70
42	1808	4520	4.5±0.20	2.00±0.20	0.15	0.85	2.60	2.20
43	1812	4532	4.5±0.30	3.20±0.20	0.30	1.10	2.00	3.0
52	2208	5720	5.7±0.40	2.00±0.20	0.15	0.85	4.20	2.20
53	2211	5728	5.7±0.40	2.80±0.20	0.15	0.85	4.20	2.80
55	2220	5750	5.7±0.40	5.00±0.40	0.30	1.40	2.50	2.70

- CT21, CT316 : (L) 3.2±0.2mm and (W)1.6±0.2mm
- T (Thickness) depends on capacitance value.
  Standard thickness is shown on the appropriate product pages.
- DR series 105, 21 size (L)(W)(T) Tolerance ±0.15mm
- CA series (please refer page 19)

Bulk Cassette

Size	EIA CODE	EIAJ CODE	L	W	T	P		P to P
						min	max	min
05	0402	1005	1.0±0.05	0.5±0.05	0.5±0.05	0.15	0.35	0.30
105	0603	1608	1.6±0.07	0.8±0.07	0.8±0.07	0.20	0.60	0.50
21	0805	2012	2.0±0.1	1.25±0.1	0.6±0.1/1.25±0.1	0.20	0.75	0.70

KYOCERA PART NUMBER: CM 21 X7R 104 K 50 A T □□□

SERIES CODE

CM	=	General Purpose	CA	=	Capacitor Arrays
CF	=	High Voltage	CU	=	Low ESR
CT	=	Low Profile			
DN/DR	=	Automotive			

SIZE CODE

SIZE		EIA (EIAJ)	SIZE		EIA (EIAJ)	SIZE		EIA (EIAJ)
03	=	0201 (0603)	21	=	0805 (2012)	52	=	2208 (5720)
05	=	0402 (1005)	316	=	1206 (3216)	53	=	5728 (2211)
105	=	0603 (1608)	32	=	1210 (3225)	55	=	2220 (5750)
F12	=	0508 (1220)/4cap	42	=	1808 (4520)	D11	=	0405 (1012)/2cap
F13	=	0612 (1632)/4cap	43	=	1812 (4532)	D12	=	0508 (1220)/2cap

DIELECTRIC CODE

CODE		EIA CODE			
CG	=	C0G (NPO)	X7S	=	X7S
X5R	=	X5R	X6S	=	X6S (Option)
X7R	=	X7R	Y5V	=	Y5V

Negative dielectric types are available on request.

CAPACITANCE CODE

Capacitance expressed in pF. 2 significant digits plus number of zeros.
For Values < 10pF, Letter R denotes decimal point,

eg.	100000pF	=	104	1.5pF	=	1R5
	0.1µF	=	104	0.5pF	=	R50
	4700pF	=	472	100µF	=	107

TOLERANCE CODE

A = ±0.05pF		D = ±0.5pF		J = ±5%		Z = -20 to +80%
B = ±0.1pF		F = ±1pF		K = ±10%		
C = ±0.25pF		G = ±2%		M = ±20%		

VOLTAGE CODE

04	=	4VDC	100	=	100VDC	1000	=	1000VDC
06	=	6.3VDC	250	=	250VDC	2000	=	2000VDC
10	=	10VDC	400	=	400VDC	3000	=	3000VDC
16	=	16VDC	630	=	630VDC	4000	=	4000VDC
25	=	25VDC						
35	=	35VDC						
50	=	50VDC						

TERMINATION CODE

A	=	Nickel Barrier	C	=	Silver (∗option)
B	=	Silver Palladium (∗option)			

PACKAGING CODE

B	=	Bulk	L	=	13" Reel Taping & 4mm Cavity pitch
C	=	Bulk Cassette	H	=	7" Reel Taping & 2mm Cavity pitch
T	=	7" Reel Taping & 4mm Cavity pitch	N	=	13" Reel Taping & 2mm Cavity pitch

OPTION

Thickness max value is indicated in CT series

EX.	125	→	1.25mm max
	095	→	0.95mm max

High Dielectric Constant

EIA Dielectric	Temperature Range	ΔCmax
X5R	–55 to 85°C	±15%
X7R	–55 to 125°C	
X7S	–55 to 125°C	±22%
X6S	–55 to 105°C	
Y5V	–30 to 85°C	–82 to +22%

Temperature Compensation Type

Electric Code Value (pF)	1B/C0G	PΔ N150	RΔ N220	SΔ N330	TΔ N470	UΔ N750	SL +350 to –1000
0.5-2.7	CK	PK	RK	SK	TK	UK	SL
3.0-3.9	CJ	PJ	RJ	SJ	TJ	UJ	SL
4.0-9.0	CH	PH	RH	SH	TH	UJ	SL
≥10	CG	PH	RH	SH	TH	UJ	SL

K = ±250ppm/°C, J = ±120ppm/°C, H = ±60ppm/°C, G = ±30ppm/°C
e.g. CG = 0±30ppm/°C, PH = –150±60ppm/°C

Note: All parts will be marked as "CG" but will conform to the above table.

Available Tolerances

Dielectric materials, capacitance values and tolerances are available in the following combinations only:

EIA Dielectric	Standard Tolerance	Capacitance
COG NTC *1	A=±0.05pF	≤0.5pF
	B=±0.1pF	≤5pF
	C=±0.25pF D=±0.50pF F=±1pF	*2 <10pF
	G=±2% J=±5% K=±10%	≥10pF E12 Series
X5R X6R X7R	*3 K=±10% M=±20%	E6 Series
Y5V	Z=–20% to +80%	E3 Series

Note:
*1 NTC : Negative Temperature Compensation types are available on request as shown on product pages.
*2 Nominal values below 10pF are available in the standard values of 0.5pF, 1.0pF, 1.5pF, 2.0pF, 3.0pF, 4.0pF, 5.0pF, 6.0pF, 7.0pF, 8.0pF, 9.0pF, 10pF.
*3 J = ±5% for X7R(X5R) is available on request.

E Standard Number

E3	E6	E12	E24 (Option)	
1.0	1.0	1.0	1.0	1.1
		1.2	1.2	1.3
	1.5	1.5	1.5	1.6
		1.8	1.8	2.0
2.2	2.2	2.2	2.2	2.4
		2.7	2.7	3.0
	3.3	3.3	3.3	3.6
		3.9	3.9	4.3
4.7	4.7	4.7	4.7	5.1
		5.6	5.6	6.2
	6.8	6.8	6.8	7.5
		8.2	8.2	9.1

Features

We offer a diverse product line ranging from ultra-compact (0.6×0.3 mm) to large (5.7×5.0 mm) components configured for a variety of temperature characteristics, rated voltages, and packages. We offer the choice and flexibility for almost any applications.

Application

This standard type is ideal for use in a wide range of applications, from commercial to industrial equipment.

Temperature Compensation Dielectrics

Size (mm)	CM03 (0201)					CM05 (0402)					CM105 (0603)		CM21 (0805)				CM316 (1206)			CM32 (1210)
Temperature Characteristics	CΔ			UΔ	SL	CΔ			UΔ	SL	CΔ		CΔ				CΔ			CΔ
Rated Voltage (VDC) / Capacitance (pF)	10	16	25	25	25	16	25	50	50	50	50	100	16	25	50	100	25	50	100	50
R10 0.1																				
R50 0.5																				
1R0 1.0																				
1R5 1.5																				
2.0																				
3.0																				
4.0																				
5.0																				
6.0																				
7.0			A	A	A			B	B	B		C								
8.0																				
9.0																				
100 10																				
120 12																				
15																				
18																				
22																				
27																				
33																				
39		A																		
47																				
56																				
68	A																			
82																				
101 100																				
121 120											C					D				
150																				
180							B	B												
220						B													D	
270															D				D	
330																			D	
390																			D	
470																			D	
560																			E	
680																			E	
820																			E	
102 1000																			E	
122 1200																			E	
1500																			E	
1800																			E	
2200														E						
2700														G				E		
3300																		E		
3900																				
4700																				
5600																				
6800																	E			H
8200													G				F			H
103 10000																				
123 12000																				
15000																				
18000																				

Thickness and standard package quantity

Size	03	05	105	*105	21, 316, 32								
Thickness (mm)	A 0.3±0.03	B 0.5±0.05	C 0.8±0.1	C 0.8±0.1	D 0.6±0.1	E 0.85±0.1	F 1.15±0.1	G 1.25±0.1	H 1.4max	I 1.6max	J 1.6±0.15	K 2.0±0.2	L 2.5±0.2
Taping(178 dia reel)	15kp(P8)	10kp(P8)	4kp(P8)	8kp(P8)	4kp(P8)	4kp(P8)	3kp(E8)	3kp(E8)	3kp(E8)	2.5kp(E8)	2.5kp(E8)	2kp(E8)	1kp(E8)
Taping(330 dia reel)	———	50kp(P8)	10kp(P8)	20kp(P8)	10kp(P8)	10kp(P8)	10kp(E8)	10kp(E8)	10kp(E8)	5kp(E8)	5kp(E8)	5kp(E8)	———

Size	43, 55			
Thickness (mm)	J 1.6±0.15	K 2.0±0.2	L 2.5±0.2	M 2.8±0.2
Taping(178 dia reel)	1kp(E12)	1kp(E12)	0.5kp(E12)	0.5kp(E12)
Taping(330 dia reel)	———	———	———	———

Note : P8 = 8mm width paper tape
E8 = 8mm width plastic tape
E12 = 12mm width plastic tape

* Carrier tape 2mm pitch from one capacitor to another.

X5R Dielectric

Size (mm)	CM03 (0201)			CM05 (0402)						CM105 (0603)							CM21 (0805)					
Rated Voltage (VDC) / Capacitance (pF)	10	16	25	4	6.3	10	16	25	50	4	6.3	10	16	25	35	50	6.3	10	16	25	35	50
101 100																						
151 150 220 330			A						B							C						
470 680 102 1000		A																				
152 1500 2200 3300	A							B							C							
4700 6800 103 10000							B							C							G	
153 15000 22000 33000				B	B	B						C	C				G	G	G	G		D E G
47000 68000 104 100000										C	C											
154 150000 220000 330000																						
470000 680000 105 1000000																						
155 1500000 2200000 3300000																						
4700000 6800000 106 10000000																						

Size (mm)	CM316 (1206)						CM32 (1210)						CM43 (1812)				CM55 (2220)
Rated Voltage (VDC) / Capacitance (pF)	6.3	10	16	25	35	50	6.3	10	16	25	35	50	6.3	10	25	50	6.3
104 100000																	
220000 470000 105 1000000					F J	F					H K	H K					
2200000 4700000 106 10000000	J	J	∗2 J	∗2 J			L	K L	I L	L			∗ L M	L	L	L	
22000000 47000000 107 100000000																	∗ L

∗ Non standard specification, please contact us for further information.

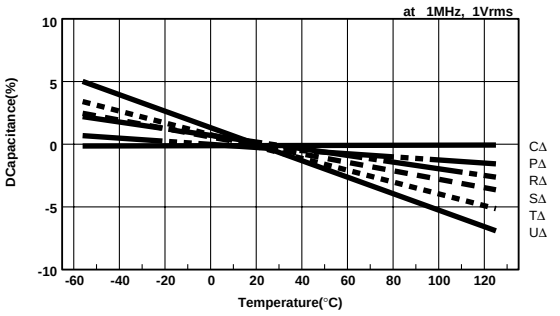
Optional Spec.

∗ Only X5R available

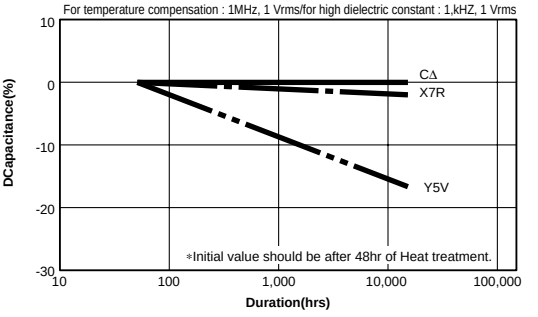
∗1 Length(L, T) tolerance ±0.15, only X5R available

∗2 Length(L, T) tolerance ±0.2, only X5R available

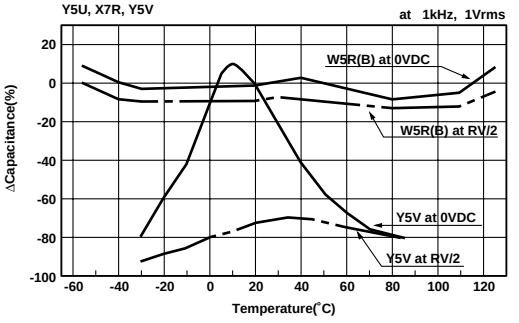
Capacitance-Temperature (temperature compensation)



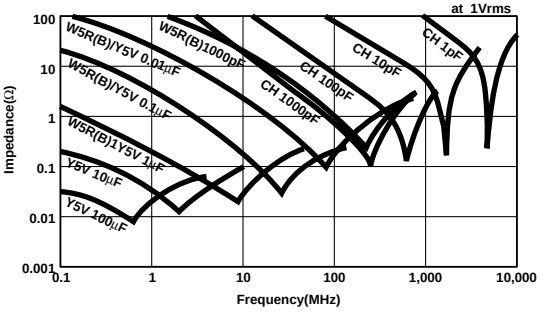
Aging (change of capacitance over time)



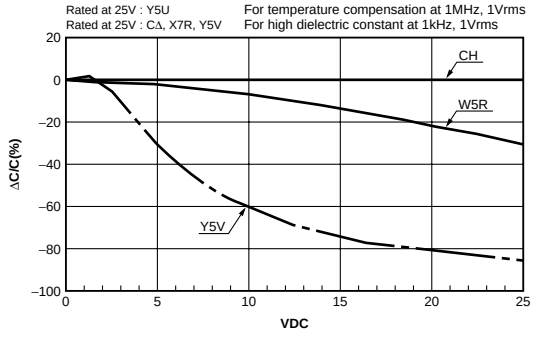
Capacitance-Temperature (high dielectric constant)



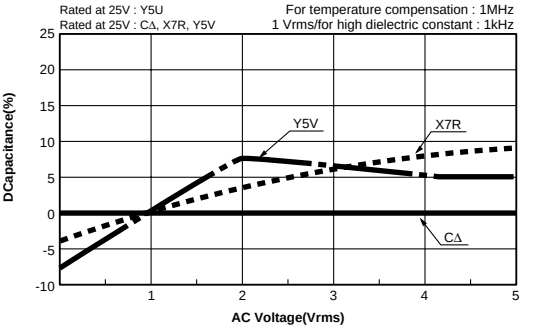
Impedance-Frequency



DC Bias



AC Voltage



Please verify individual characteristics at the design stage to ensure total suitability

Test conditions and Specification for Temperature Compensation type(C* to U* • SL characteristics)

Test Items		Specification (C: nominal capacitance)	Test Conditions
Capacitance Value		Within tolerance	C≤1000pF: 1MHz±10%, 0.5 to 5Vrms C>1000pF: 1kHz±10%, 0.5 to 5Vrms
Q		C≥30pF: Q≥1000 C<30pF: Q≥400+20C	
Insulation resistance (IR)(∗6)		10,000MΩ or 500MΩ•μF min, whichever is less	Measured after the rated voltage is applied for one minute at normal room temperature and humidity. (∗4)
Dielectric Resistance (∗6)		No problem observed	(∗1) Apply 3 times of the rated voltage for 1 to 5 seconds.
Appearance		No problem observed	Microscope(10×magnification)
Termination strength (∗2)		No problem observed	Apply a sideward force of 500g(5N) (∗7) to a PCB-mounted sample.
Bending strength (∗2)		No mechanical damage at 1mm bent	Glass epoxy PCB (t=1.6mm); fulcrum Spacing: 90mm; for 10 seconds.
Vibration test	**Appearance**	No significant change is detected.	Vibration frequency: 10 to 55(Hz) Amplitude: 1.5mm Sweeping condition: 10→55→10Hz/min In X, Y and Z directions: 2 hours each Total 6 hours
	ΔC	Within tolerance	
	Q	C≥30pF: Q≥1000 C<30pF: Q≥400+20C	
Soldering heat resistance	**Appearance**	No significant change is detected.	Soak the sample in 260°C±5°C solder for 10±0.5seconds and place in a room at normal temperature and humidity; measure after 24±2hours. (Preheating Conditions) Order 1: 80 to 100°C, 2minutes Order 2: 150 to 200°C, 2minutes
	ΔC	±2.5% or ±0.25pF max, whichever is larger.	
	Q	C≥30pF: Q≥1000 C<30pF: Q≥400+20C	
	IR (∗6)	10,000MΩ or 500MΩ•μF min, whichever is smaller	
	Withstand voltage (∗6)	Resists without problem	
Solderability		Ni/Br termination: 90% min	Soaking Condition Sn62 Solder: 235±5°C, 2±0.5sec. Sn-3Ag-0.5Cu: 245±5°C, 3±0.5sec.
Temperature cycle (∗3)	**Appearance**	No significant change is detected.	(Cycle) Normal room temperature (3min)→ Lowest operation temperature (30min)→ Normal room temperature (3min)→ Highest operation temperature (30min)→ After five cycles (∗3), measure after 24±2hours.
	ΔC	±2.5% or ±0.25pF max, whichever is larger.	
	Q	C≥30pF: Q≥1000 C<30pF: Q≥400+20C	
	IR (∗6)	10,000MΩ or 500MΩ•μF min, whichever is samller	
	Withstand voltage (∗6)	Resists without problem	
Humidity test (∗5)	**Appearance**	No significant change is detected.	Measure the test sample after storing it 24±2hours at a temperature of 40°C±2°C and a relative humidity of 90-95% Rh. for 500+24/–0hours.
	ΔC	±7.5% or ±0.75pF max, whichever is larger.	
	Q	C≥30pF: Q≥200 C<30pF: Q≥100+10C/3	
	IR (∗6)	500MΩ or 25MΩ•μF min, whichever is smaller	
High-temperature with loading	**Appearance**	No significant change is detected.	After applying (∗1) twice of the rated voltage at a temperature of 125±3°C for 1000+48/–0hours, measure the sample after storing 24±2hours.
	ΔC	±3% or ±0.3pF max, whichever is larger.	
	Q	C≥30pF: Q≥350 10pF≤C<30pF: Q≥275+5C/2 C<10pF: Q≥200+10C	
	IR (∗6)	1,000MΩ or 50MΩ•μF min, whichever is smaller	

∗1 For the CF series, use 1.5 times when the rated voltage is 250V; use/1.2 times when the rated voltage exceeds 630V.
∗2 Except CT series
∗3 Different specification for Nickel Barrier termination DN/DR series. (Alumina Substrate)
∗4 Apply 500V for 1minite in case the rated voltage is 1000V or higher.
∗5 Except CF series.
∗6 The charge and discharge current of the capacitor must not exceed 50mA.
∗7 2N at 0201 Size

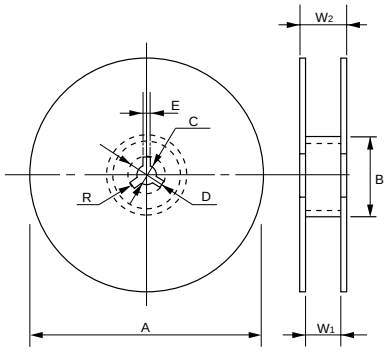
Test conditions and Specification for High Dielectric Type (X5R, X7R, Y5V)

Test Items		Specification X7R/X5R	Specification Y5V	Test Condition
Capacitance Value		Within tolerance		Do previous treatment (*8, *14) Capacitance / Fire / Vol C≤10μF / 1kHz±10% / 1.0±0.1Vrms C>10μF / 120Hz±10% / 0.5±0.1Vrms
tanδ(%)		2.5%max, 3.5%max (*2) 5.0%max (*3)	5.0%max, 7.0%max (*13) 9.0%max (*4), 12.5%max (*5)	
Insulation resistance (IR) (*15)		10,000MΩ or 500MΩ•μF max, whichever is less		Measured after the rated voltage is applied for 2minutes at normal room temperature and humidity. (*10)
Dielectric Resistance (*1, *15)		No problem observed		(*1) Apply 2.5 times of the rated voltage for 1 to 5 seconds.
Appearance		No problem observed		Microscope(10×magnification)
Termination strength (*6)		No problem observed		Apply a sideward force of 500g(5N) (*16) to a PCB-mounted sample.
Bending strength test (*6)		No problem observed at 1mm bent		Glass epoxy PCB (t=1.6mm); fulcrum Spacing: 90mm; for 10 seconds.
Vibration test	**Appearance**	No significant change is detected.		Vibration frequency: 10 to 55(Hz) Amplitude: 1.5mm Sweeping condition: 10→55→10Hz/min In X, Y and Z directions: 2 hours each Total 6 hours
	ΔC	Within tolerance		
	tanδ(%)	Satisfies the initial value.		
Soldering heat resistance	**Appearance**	No significant change is detected.		Do previous treatment (*8) Soak the sample in 260°C±5°C solder for 10±0.5seconds and place in a room at normal temperature and humidity; measure after 48±4hours. (Preheating Conditions) Order / Temperature / Time 1 / 80 to 100°C / 2minutes 2 / 150 to 200°C / 2minutes
	ΔC	Within ±7.5%	Within ±20%	
	tanδ(%)	Satisfies the initial value.		
	IR (*15)	10,000MΩ or 500MΩ•μF max, whichever is smaller		
	Withstand voltage (*15)	Resists without problem		
Solderability		Ni/Br termination: 90% min Ag/Pd termination: 75%min		Soaking Condition Sn62 Solder / 235±5°C / 2±0.5sec. Sn-3Ag-0.5Cu / 245±5°C / 3±0.5sec.
Temperature cycle (*7)	**Appearance**	No significant change is detected.		Do previous treatment (*8) (Cycle) Normal room temperature (3min)→ Lowest operation temperature (30min)→ Normal room temperature (3min)→ Highest operation temperature (30min)→ After five cycles (*7), measure after 48±4hours.
	ΔC	Within ±7.5%	Within ±20%	
	tanδ(%)	Satisfies the initial value.		
	IR (*15)	10,000MΩ or 500MΩ•μF max, whichever is smaller		
	Withstand voltage (*15)	Resists without problem		
Humidity test (*11)	**Appearance**	No significant change is detected.		Do previous treatment (*9) After storing it at a temperature of 40°C±2°C and a relative humidity of 90-95% for 500+24/–0hours, measure the sample after storing 48±4hours.
	ΔC	Within ±12.5%	Within ±30%	
	tanδ(%)	200% max of initial value	150% max of initial value	
	IR (*15)	500MΩ or 25MΩ•μF max, whichever is smaller		
High-temperature with loading	**Appearance**	No significant change is detected.		Do previous treatment (*9) After applying twice (*1) of the rated voltage at the highest operating temperature for 1000+48/–0hours, measure the sample after storing 48±4hours.
	ΔC	Within ±12.5%	Within ±30%	
	tanδ(%)	200% max of initial value	150% max of initial value	
	IR (*15)	1,000MΩ or 50MΩ•μF max, whichever is smaller		

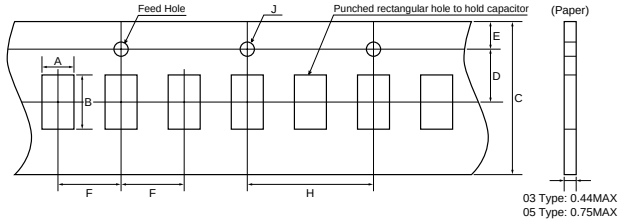
*1 For CF series, use 1.5 times when the rated voltage is 250V and 500V; Use 1.2 times when the rated voltage exceeds 630V. Use 1.5 times when the rated voltage is 4V.
*2 Apply to X5R 16V/25V type, X7R 10V/16V type, CM316X7R564 to 105(25V type).
*3 Apply to X5R 6.3V/10V type, CT05X7R123 to 223(10V type),X7R 6.3V type.
*4 Apply to Y5V 16V type, CM32Y5V335 to 106 (25V Type). Except 12.5% for CT21Y5V105/16V.
*5 Apply to Y5V 6.3V/10V type. Apply 16% to CM21Y5V106/CM316Y5V226.
*6 Exclude CT series with thickness of less than 0.66mm and CA series.
*7 Different Specification for Nickel Barrier termination DN/DR series. (Alumina Substrate)
*8 Keep specimen at 150°C+0/–10°C for one hour, leave specimen at room ambient for 48±4 hours.
*9 Apply the same test condition for one hour, then leave the specimen at room ambient for 48±4 hours.
*10 For the CF series over 1000V, apply 500V for 1 minutes at room ambient.
*11 Except CF series.
*12 Apply to X5R/4V type.
*13 Apply to 25V series of CM105Y5V154 over, CM21Y5V105 over, 316Y5V155 over.
*14 Measurement condition 1kHz, 1Vrms for Y5V, C < 47μF type.
*15 The charge/discharge current of the capacitor must not exceed 50mA.
*16 2N at 0201 Size

Tape and Reel

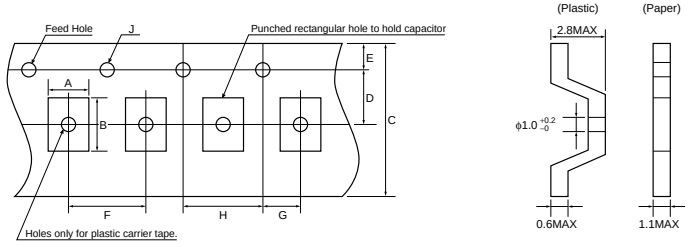
• Reel



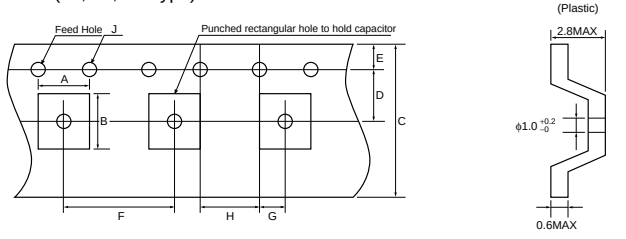
F=2mm(03, 05, 105 Type)



F=4mm(105, D11, D12, F12, F13, 21, 316, 32, 42, 52 Type)

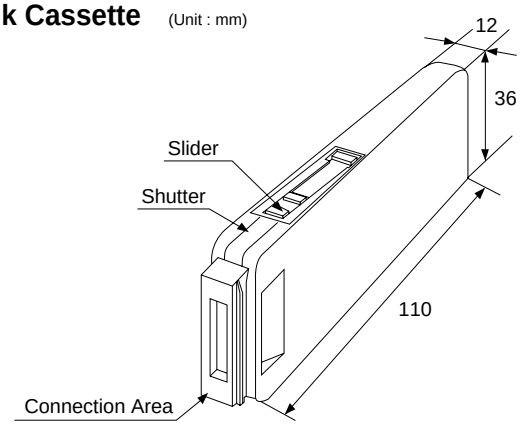


F=8mm(43, 53, 55 Type)



Bulk Cassette

(Unit : mm)



Reel (code : T)

(Unit : mm)

Code / Reel	A	B	C	D
7-inch Reel (CODE : T, H)	178±2.0	ϕ60min	13±0.5	21±0.8
13-inch Reel (CODE : L, N)	330±2.0	ϕ100±1.0		
Code / Reel	**E**	**W1**	**W2**	**R**
7-inch Reel (CODE : T, H)	2.0±0.5	10.0±1.5	16.5max	1.0
13-inch Reel (CODE : L, N)		9.5±1.0		

∗Carrier tape width 8mm. For size 42(1808) or over, Tape width 12mm and W1 : 14±1.5, W2 : 18.4mm max

Carrier Tape

(Unit : mm)

Type	A	B	F
03 (0.6×0.3)	0.37±0.03	0.67±0.03	2.0±0.05
05 (1.0×0.5)	0.65±0.1	1.15±0.1	2.0±0.05
105 (1.6×0.8)	1.0±0.2	1.8±0.2	4.0±0.1
D11 (1.37×1.0)	1.15±0.1	1.55±0.1	4.0±0.1
D12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
F12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
F13 (1.6×3.2)	2.0±0.2	3.6±0.2	4.0±0.1
21 (2.0×1.25)	1.5±0.2	2.3±0.2	4.0±0.1
316 (3.2×1.6)	2.0±0.2	3.6±0.2	4.0±0.1
32 (3.2×2.5)	2.9±0.2	3.6±0.2	4.0±0.1
42 (4.5×2.0)	2.4±0.2	4.9±0.2	4.0±0.1
43 (4.5×3.2)	3.6±0.2	4.9±0.2	8.0±0.1
52 (5.7×2.0)	2.4±0.2	6.0±0.2	4.0±0.1
53 (5.7×2.8)	3.2±0.2	6.0±0.2	8.0±0.1
55 (5.7×5.0)	5.3±0.2	6.0±0.2	8.0±0.1

(Unit : mm)

F	Carrier Tape	C	D	E	G	H	J
2.0 ±0.05	8mm Paper	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	2.0 ±0.05	4.0 ±0.1	1.5 +0.1/−0
4.0 ±0.1	8mm Plastic						
8.0 ±0.1	12mm Plastic	12.0 ±0.3	5.5 ±0.05				

Circuit Design

1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.

2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability.
   Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.

3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications.
   Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur.
   The capacitor has a loss, and may self-heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution.
   When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20ºC.

4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage.
   In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
   Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.

5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer.
   In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.

6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage.
   Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.

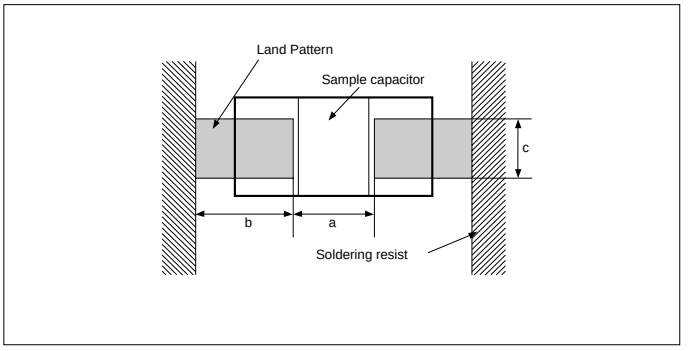
7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications.
   In addition, it is a common piezo phenomenon of high dielectric products to have some Voltage due to vibration or to have noise due to Voltage change. Please contact sales in such case.

8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.

Storage

1. If the component is stored in minimal packaging (a heat-sealed or chuck-type plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
2. Keep storage place temperature +5 to +35 degree C, humidity 45 to 70% RH.
3. The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
4. Precautions 1)-3) apply to chip capacitors packaged in carrier tapes and bulk cases.
5. The solderability is assured for 12 months from our shipping date (six months for silver palladium) if the above storage precautions are followed.
6. Chip capacitors may crack if exposed to hydrogen (H_2) gas while sealed or if coated with silicon, which generates hydrogen gas.

Dimensions for recommended typical land



When mounting the capacitor to the substrate, it is important to consider carefully that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it is mounted.

a) The greater the amount of solder, the greater the stress to the elements. As this may cause the substrate to break or crack, it is important to establish the appropriate dimensions with regard to the amount of solder when designing the land of the substrate.
b) In the situation where two or more devices are mounted onto a common land, separate the device into exclusive pads by using soldering resist

Standard

(Unit : mm)

Size	L×W	a	b	c
03	0.6×0.3	0.20 to 0.30	0.25 to 0.35	0.30 to 0.40
05	1.0×0.5	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60
105	1.6×0.8	0.70 to 1.00	0.80 to 1.00	0.60 to 0.80
21	2.0×1.25	1.00 to 1.30	1.00 to 1.20	0.80 to 1.10
316	3.2×1.6	2.10 to 2.50	1.10 to 1.30	1.00 to 1.30
32	3.2×2.5	2.10 to 2.50	1.10 to 1.30	1.90 to 2.30
42	4.5×2.0	2.50 to 3.20	1.80 to 2.30	1.50 to 1.80
43	4.5×3.2	2.50 to 3.20	1.80 to 2.30	2.60 to 3.00
52	5.7×2.0	4.20 to 4.70	2.00 to 2.50	1.50 to 1.80
53	5.7×2.8	4.20 to 4.70	2.00 to 2.50	2.20 to 2.60
55	5.7×5.0	4.20 to 4.70	2.00 to 2.50	4.20 to 4.70

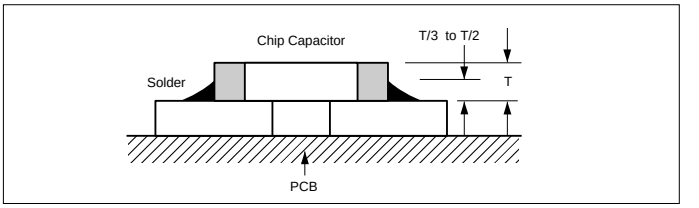
∗ CA series : Please refer Page 19.

DN/DR Automotive Series

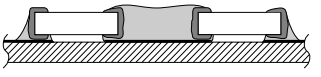
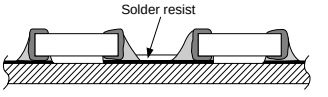
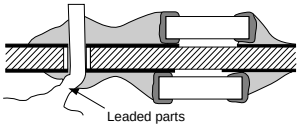
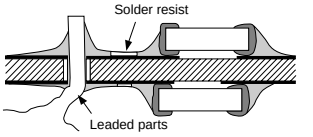
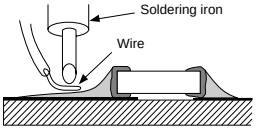
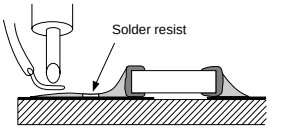
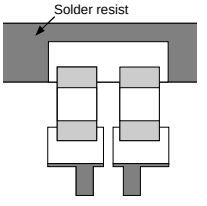
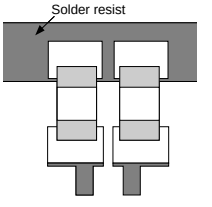
(Unit : mm)

Size	L×W	a	b	c
105	1.6×0.8	0.60 to 0.90	0.80 to 1.00	0.70 to 1.00
21	2.0×1.25	0.90 to 1.20	0.80 to 1.20	0.90 to 1.40
316	3.2×1.6	1.40 to 1.90	1.00 to 1.30	1.30 to 1.80

Ideal Solder Thickness



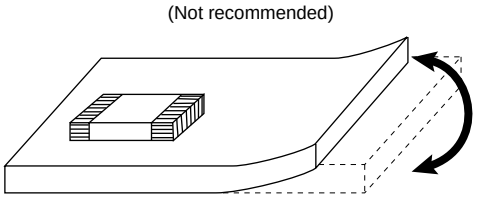
Typical mounting problems

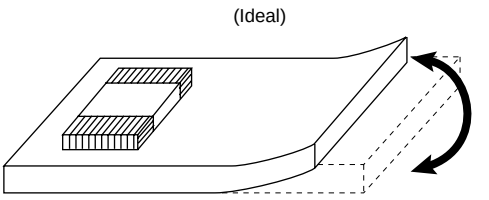
Item	Not recommended example	Recommended example/Separated by solder resist
Multiple parts mount		
Mount with leaded parts		
Wire soldering after mounting		
Overview		

Mounting Design

The chip could crack if the PCB warps during processing after the chip has been soldered.

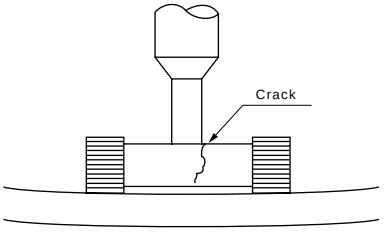
Recommended chip position on PCB to minimize stress from PCB warpage

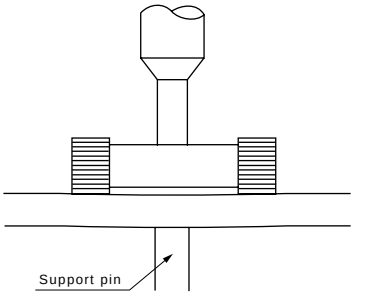




Actual Mounting

1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
2) During mounting, set the nozzle pressure to a static load of 100 to 300 gf.
3) To minimize the shock of the vaccum nozzle, provide a support pin on the back of the PCB to minimize PCB flexture.





4) When the positioning hook begins to wear, unstable mechanical shock may be applied to the chip capacitor, resulting in cracking.
5) To reduce the possibility of chipping and cracks, minimize vibration to chips stored in a bulk case.
6) The discharge pressure must be adjusted to the part size. Verify the pressure during setup to avoid fracturing or cracking the chips capacitors.

Resin Mold

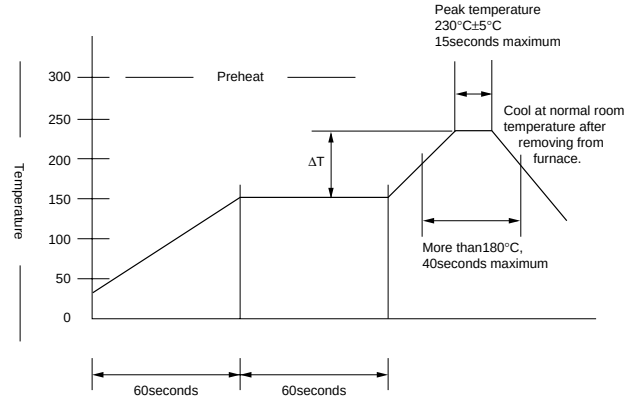
1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.

Soldering Method

1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 130 degree Celsius.
2) The product size 1.0×0.5mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of over 3.2×2.5mm, 0.6×0.3mm, and capacitor arrays can be used in reflow.
   Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
3) Please see our recommended soldering conditions.
   Please contact us if you use lead free solder because the peak temperature of lead free is different from non-lead free.

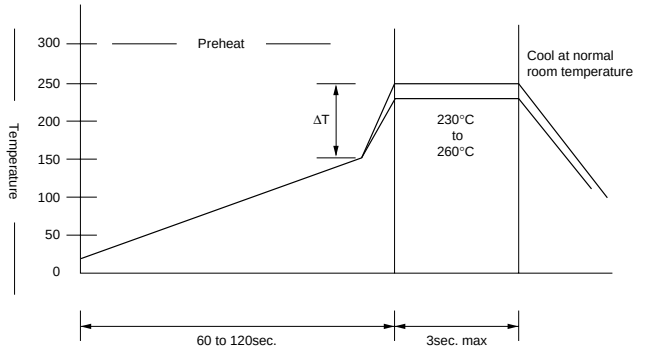
Recommendable Temperature Profile(62Sn Solder)

Reflow



① Minimize soldering time.
② Ensure that allowable temperature difference does not exceed 130˚C.

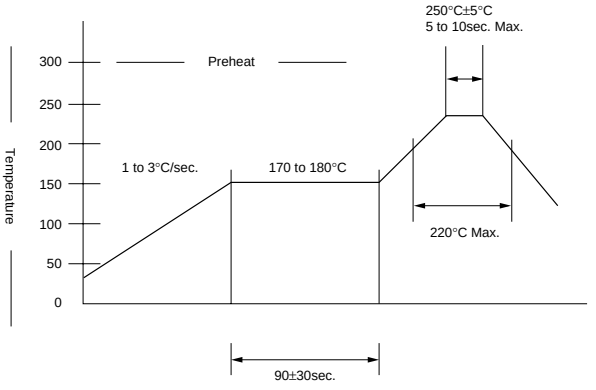
Wave



① Ensure that the chip capacitor is preheated adequately.
② Ensure that the temperature difference (ΔT) does not exceed 150°C.
③ Cool naturally after soldering.
④ Stop wave in more than CM32.

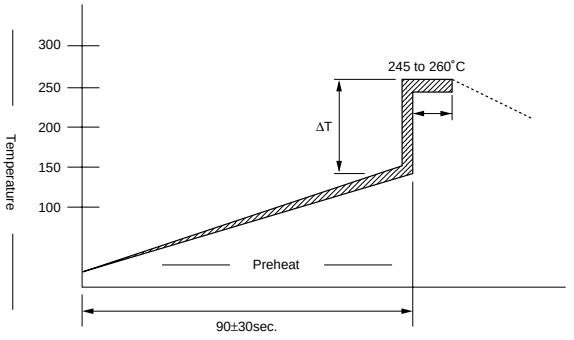
Recommendable Temperature Profile(Sn-3Ag-0.5Cu)

Reflow



① Minimize soldering time.
② Ensure that allowable temperature difference does not exceed 130˚C.

Wave



① Ensure that the chip capacitor is preheated adequately.
② Ensure that the temperature difference (ΔT) does not exceed 150°C.
③ Cool naturally after soldering.

Sodering iron

1) Temperature of iron chip.
2) Wattage.
3) Tip shape of soldering iron.
4) Soldering Time.
5) Cautions
   a) Pre-heating is necessary Rapid heating must be avoided.
      Delta T≤130˚C.
   b) Avoid direct touching to capacitors.
   c) Avoid rapid cooling after soldering. Natural cooling is recommended.